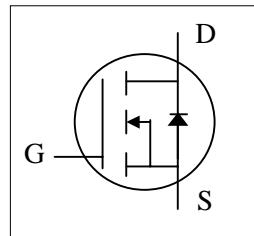
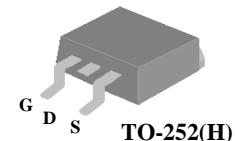
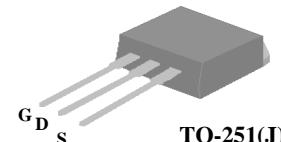




- ▼ Simple Drive Requirement
- ▼ Lower On-resistance
- ▼ Fast Switching Characteristic
- ▼ RoHS Compliant & Halogen-Free



$BV_{DSS}$	75V
$R_{DS(ON)}$	8mΩ
$I_D$	75A



## Description

AP94T07 series are from Advanced Power innovative design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.

The TO-252 package is widely preferred for all commercial-industrial surface mount applications using infrared reflow technique and suited for high current application due to the low connection resistance. The through-hole version (AP94T07GJ) are available for low-profile applications.

## Absolute Maximum Ratings@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	75	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_c = 25^\circ\text{C}$	Drain Current, $V_{GS} @ 10\text{V}^3$	75	A
$I_D @ T_c = 100^\circ\text{C}$	Drain Current, $V_{GS} @ 10\text{V}$	58	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	300	A
$P_D @ T_c = 25^\circ\text{C}$	Total Power Dissipation	125	W
$P_D @ T_A = 25^\circ\text{C}$	Total Power Dissipation <sup>4</sup>	2.4	W
$T_{STG}$	Storage Temperature Range	-55 to 175	°C
$T_J$	Operating Junction Temperature Range	-55 to 175	°C

## Thermal Data

Symbol	Parameter	Value	Units
$R_{thj-c}$	Maximum Thermal Resistance, Junction-case	1.2	°C/W
$R_{thj-a}$	Maximum Thermal Resistance, Junction-ambient (PCB mount) <sup>4</sup>	62.5	°C/W
$R_{thj-a}$	Maximum Thermal Resistance, Junction-ambient	110	°C/W



# AP94T07GH/J-HF

## Electrical Characteristics@ $T_j=25^\circ C$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	75	-	-	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10V, I_D=40A$	-	-	8	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2	-	5	V
$g_{fs}$	Forward Transconductance	$V_{DS}=10V, I_D=40A$	-	55	-	S
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=60V, V_{GS}=0V$	-	-	25	$\mu A$
$I_{GSS}$	Gate-Source Leakage	$V_{GS}=+20V, V_{DS}=0V$	-	-	$\pm 100$	$nA$
$Q_g$	Total Gate Charge <sup>2</sup>	$I_D=40A$	-	58	92	$nC$
$Q_{gs}$	Gate-Source Charge	$V_{DS}=60V$	-	14	-	$nC$
$Q_{gd}$	Gate-Drain ("Miller") Charge	$V_{GS}=10V$	-	29	-	$nC$
$t_{d(on)}$	Turn-on Delay Time <sup>2</sup>	$V_{DS}=40V$	-	13	-	ns
$t_r$	Rise Time	$I_D=40A$	-	80	-	ns
$t_{d(off)}$	Turn-off Delay Time	$R_G=1\Omega$	-	26	-	ns
$t_f$	Fall Time	$V_{GS}=10V$	-	12	-	ns
$C_{iss}$	Input Capacitance	$V_{GS}=0V$	-	2350	3760	$pF$
$C_{oss}$	Output Capacitance	$V_{DS}=25V$	-	390	-	$pF$
$C_{rss}$	Reverse Transfer Capacitance	f=1.0MHz	-	245	-	$pF$
$R_g$	Gate Resistance	f=1.0MHz	-	1.3	-	$\Omega$

## Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{SD}$	Forward On Voltage <sup>2</sup>	$I_S=40A, V_{GS}=0V$	-	-	1.3	V
$t_{rr}$	Reverse Recovery Time <sup>2</sup>	$I_S=10A, V_{GS}=0V,$	-	46	-	ns
$Q_{rr}$	Reverse Recovery Charge	dl/dt=100A/ $\mu s$	-	83	-	$nC$

## Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3.Package limitation current is 75A.
- 4.Surface mounted on 1 in<sup>2</sup> copper pad of FR4 board

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

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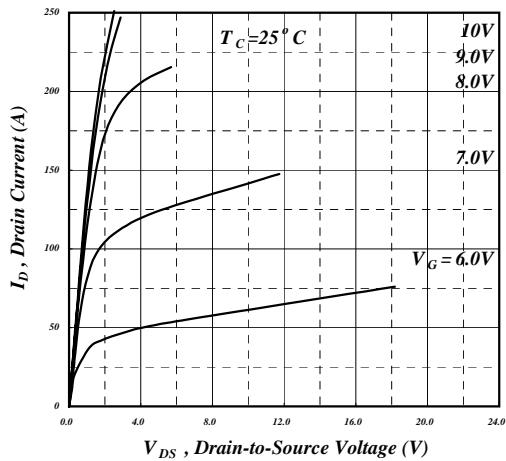


Fig 1. Typical Output Characteristics

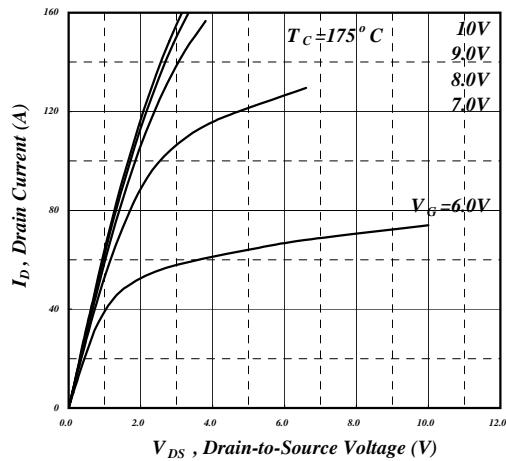


Fig 2. Typical Output Characteristics

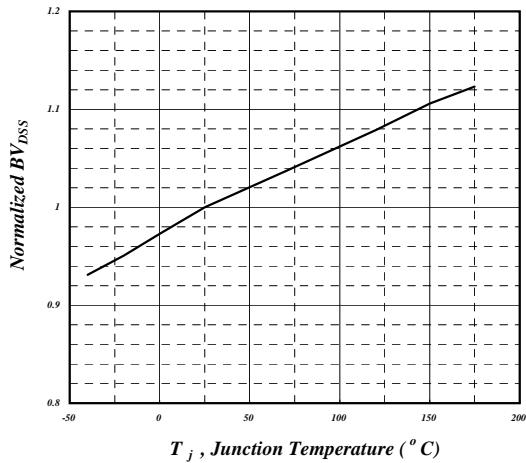
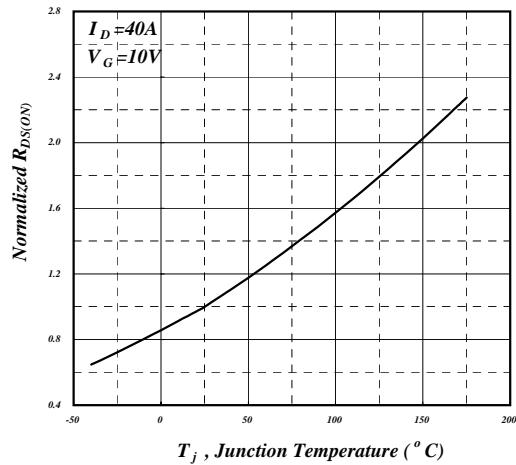
Fig 3. Normalized  $BV_{DSS}$  v.s. Junction Temperature

Fig 4. Normalized On-Resistance v.s. Junction Temperature

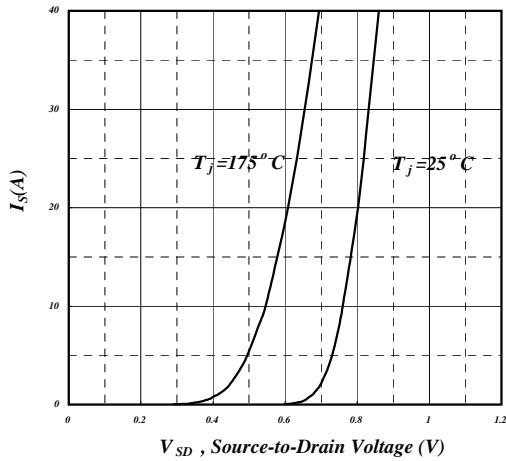


Fig 5. Forward Characteristic of Reverse Diode

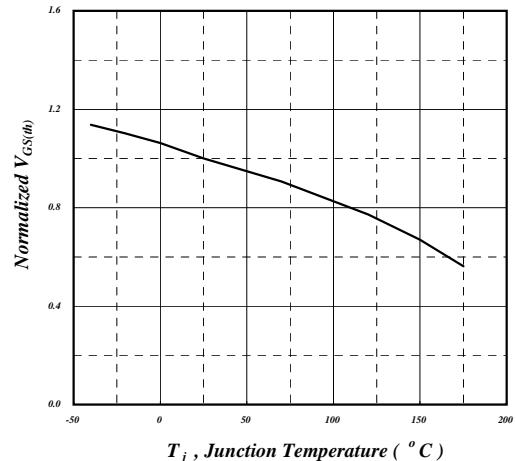
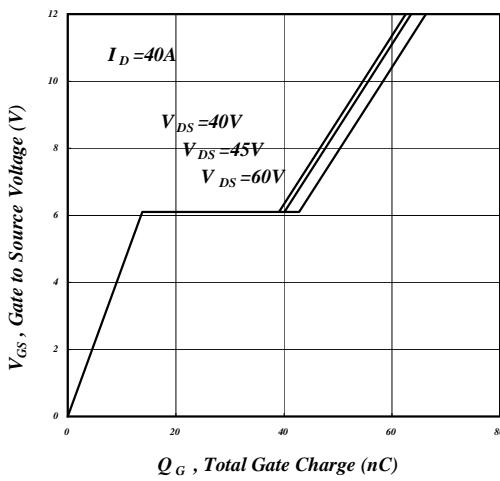
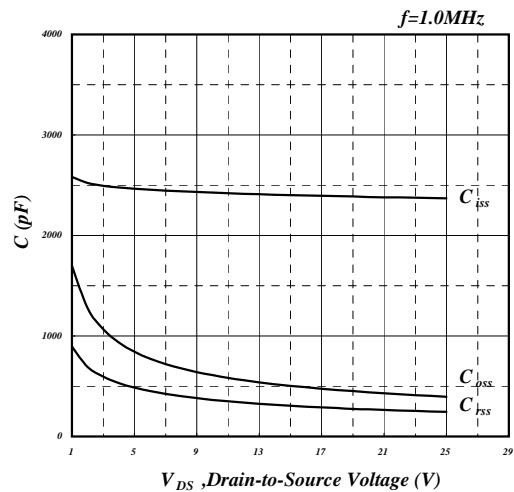


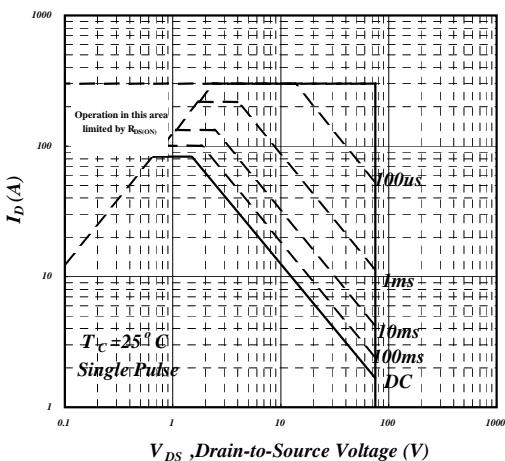
Fig 6. Gate Threshold Voltage v.s. Junction Temperature



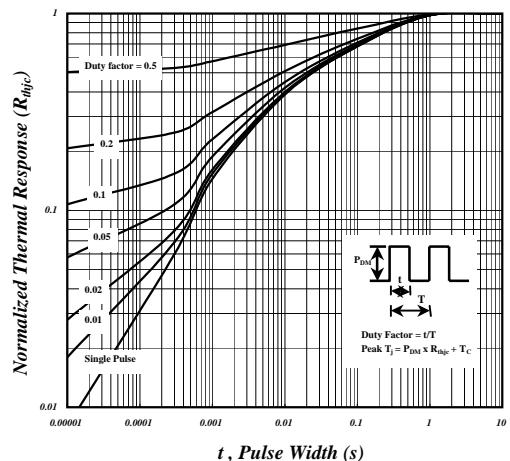
**Fig 7. Gate Charge Characteristics**



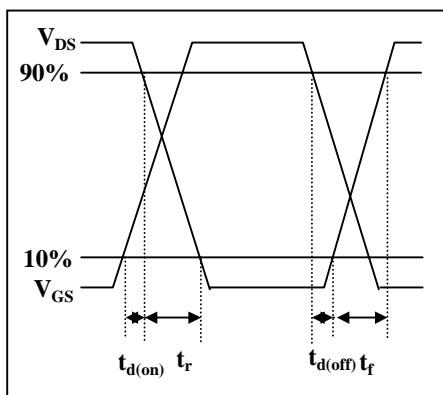
**Fig 8. Typical Capacitance Characteristics**



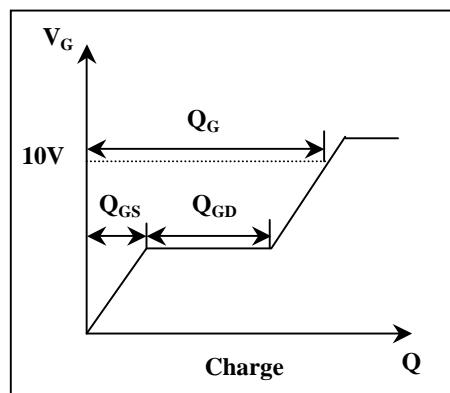
**Fig 9. Maximum Safe Operating Area**



**Fig 10. Effective Transient Thermal Impedance**



**Fig 11. Switching Time Waveform**

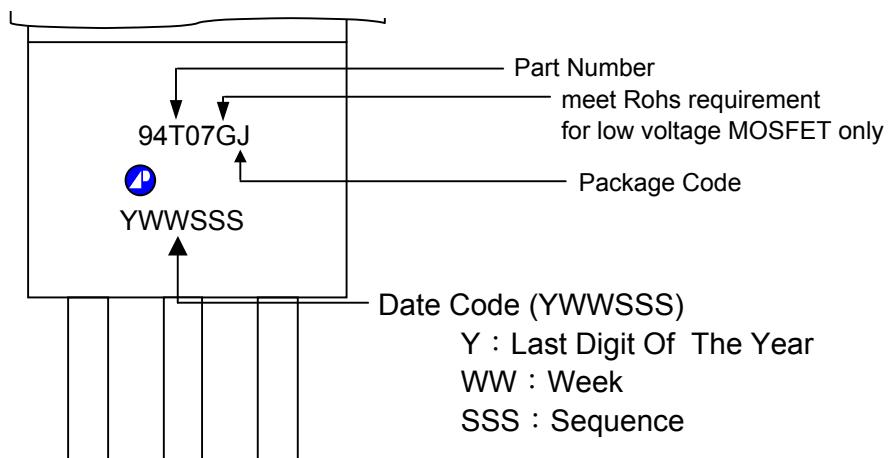


**Fig 12. Gate Charge Waveform**

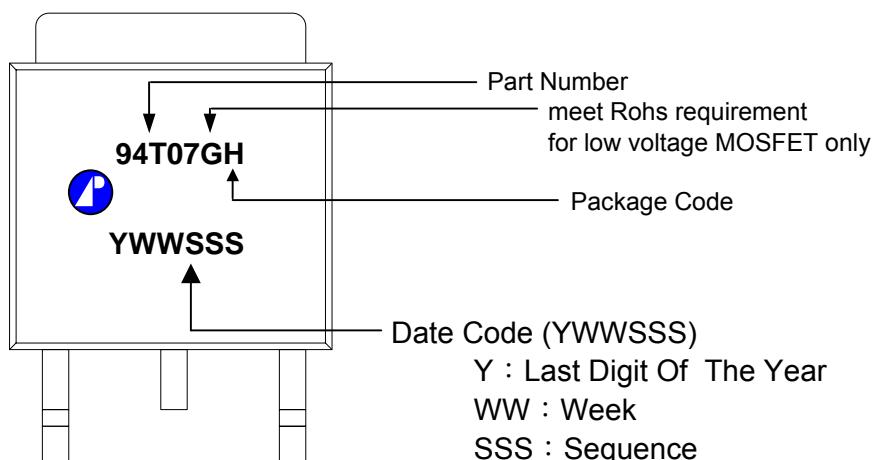


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TO-251



TO-252



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